MECHANICAL DESIGN ENGINEER, ELECTRONICS PACKAGING

Posting ID: EM20328020
Company: Cesium
Position Type: Full-Time
College Major(s): Mechanical Engineering (ME)

Company Website: https://cesium.com/
Work Location: Austin, TX
College Level(s): Undergraduate-Senior, Graduate Student, PhD. Student, Alumni

OVERVIEW

We are looking to add a Mechanical Design Engineer to our team. If you are great at what you do, enjoy working in a startup environment, and are passionate about developing leading-edge hardware for satellites, spacecraft, and aerospace systems, we would like to hear from you.

Roles and Responsibilities
In this position, you will be responsible for mechanical designs of Cesium products through all phases of the development process. The ideal candidate will be proficient in electronics packaging design, mechanical simulations and analyses, computer-aided design (CAD), spacecraft mechanical interfaces, and environmental qualification of electronic assemblies.

As a Cesium mechanical team member, you will be responsible for mechanical designs from initial concept design through requirements definition, detailed design, simulation, analysis, manufacturing, testing, qualification, and in-orbit support of Cesium's products. Required skills and experience include thermal management design, precision machining principles, thermal simulation and analysis, shock and vibration simulation and analysis, electromagnetic interference/compatibility (EMI/EMC) mitigation techniques, geometric dimensioning and tolerancing (GD&T), finite element analysis (FEA), and cost analysis to develop, validate, and optimize mechanical designs.

The successful candidate will also present engineering design review materials to our customers and executive team, as well as participate in proposal-writing efforts. As such, excellent written and verbal communication skills are required.

Education and Qualifications
Bachelor of Science (BS) or Master of Science (MS) degree in Mechanical or Aerospace Engineering from an accredited university or institution.
Minimum of 2 years of industry experience in design and analysis of electronics packaging, including thermal, vibration, and stress dynamics. More experienced candidates are also
encouraged to apply.
Familiarity with electronics assemblies and experience working closely with electrical engineers.
Experience with professional mechanical and FEA CAD tools, such as Solidworks Simulation.
Experience with CNC manufacturing.
Experience with EMI/EMC mitigation techniques.
Excellent written and verbal communication skills.

Preferred Skills
Aerospace industry design, development, and qualification.

How to Apply
https://cesiumastro.breezy.hr/p/ebca80ea38ba?source=directemployers